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New OpenVPX Development Platform from Pixus Features Mix of Conduction and Air Cooled Card Guides

Waterloo, Ontario — Mar 20, 2018 – Pixus Technologies, a provider of embedded computing and enclosure solutions, now offers OpenVPX platforms with a mix of card guides that allow IEEE 1101.10 air cooled and IEEE 1101.2 conduction cooled boards to be tested in the same enclosure.

The Pixus OpenVPX Development Chassis allows the use of Rear Transition Modules (RTMs) and up to 8 backplane slots at a 1” pitch. Pixus offers various slot sizes and profiles of 3U and 6U OpenVPX backplanes compliant to the VITA 65 specification. A modular power supply allows various modules for +3.3V, +5V, +/- 12V, auxiliary voltages, and other options to be assembled for the ideal power output for each configuration.

Pixus offers OpenVPX chassis in 19” rackmount, development/desktop, Air Transport Rack (ATR), and ruggedized versions. The company also provides components, chassis platforms, and modular instrumentation cases in various form factors.

About Pixus Technologies

Leveraging over 25 years of innovative standard products, the Pixus team is comprised of industry experts in electronics packaging. Founded in 2009 by senior management from Kaparel Corporation, a Rittal company, Pixus Technologies' embedded backplanes and systems are focused primarily on ATCA, OpenVPX, MicroTCA, and custom designs. Pixus also has an extensive offering of VME-based and cPCI-based solutions. In May 2011, Pixus Technologies became the sole authorized North and South American supplier of the electronic packaging products previously offered by Kaparel Corporation and Rittal.